Tin-Lead
SLOTOLET K 10 1

Tin-Lead SLOTOLET K 10 1 is a strong acidic fluoride-free process for the deposition of matt tin-lead layers. The alloy composition can be varied over a wide range. The special focus is on the eutectic mixture (35 % lead) and layers with a low lead content of 5 - 15 %. Within the chosen electrolyte composition the ratio of the alloy is very stable over a wide current density range.

The co-deposition of organic compounds in the coating is low; the carbon content is 0.005 %. Solderability following ageing tests is very good.

It should be noted that the organic additives can be fully analyzed. This allows on the one hand a control of possible organic impurities, e.g. in PCB manufacturing, and on the other hand a exact monitoring and documentation of all electrolyte parameters.

The layers deposited from Tin-Lead SLOTOLET K 10 1 are very smooth and therefore favour also e.g. the forming process of connection legs at IC makers.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance only. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:
Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).
The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.
For the storage of chemical products the TRGS 510 must be followed.
If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.